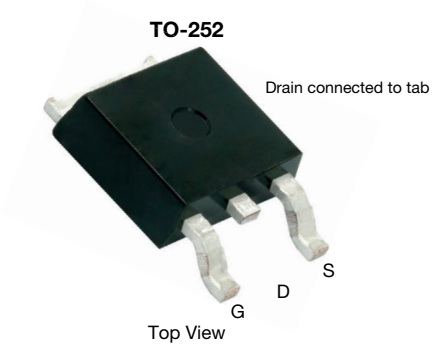
N-Channel 100 V (D-S) MOSFET

PRODUCT SUMMARY			
V_{DS} (V)	$R_{DS(on)}$ (Ω)	I_D (A) [a]	Q_g (TYP.)
100	0.0260 at V_{GS} = 10 V	35	31 nC
	0.0375 at V_{GS} = 7 V	31	

FEATURES

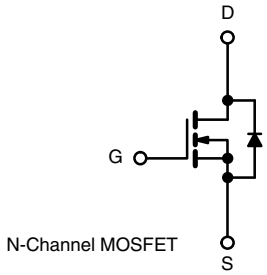
- TrenchFET® power MOSFET
- 100 % UIS tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

RoHS COMPLIANT



APPLICATIONS

- Primary side switch



Ordering Information:
SUD35N10-26P-E3 (lead (Pb)-free)

ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C, unless otherwise noted)				
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-Source Voltage		V_{DS}	100	V
Gate-Source Voltage		V_{GS}	± 20	
Continuous Drain Current (T_J = 175 °C)	T_C = 25 °C	I_D	35	A
	T_C = 70 °C		32	
	T_A = 25 °C		12 [b, c]	
	T_A = 70 °C		10 [b, c]	
Pulsed Drain Current		I_{DM}	40	
Continuous Source-Drain Diode Current	T_C = 25 °C	I_S	50 [e]	
	T_A = 25 °C		6.9 [b, c]	
Avalanche Current Pulse	L = 0.1 mH	I_{AS}	33	
Single Pulse Avalanche Energy		E_{AS}	55	mJ
Maximum Power Dissipation	T_C = 25 °C	P_D	83	W
	T_C = 70 °C		58	
	T_A = 25 °C		8.3 [b, c]	
	T_A = 70 °C		5.8 [b, c]	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	-55 to +175	°C

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT
Maximum Junction-to-Ambient [b, d]	t ≤ 10 s	R_{thJA}	15	18	°C/W
Maximum Junction-to-Case	Steady State	R_{thJC}	1.5	1.8	

Notes

a. Based on T_C = 25 °C.
b. Surface mounted on 1" x 1" FR4 board.
c. t = 10 s.
d. Maximum under steady state conditions is 50 °C/W.
e. Calculated based on maximum junction temperature. Package limitation current is 50 A.

SPECIFICATIONS (T_J = 25 °C, unless otherwise noted)						
PARAMETER	**SYMBOL**	**TEST CONDITIONS**	**MIN.**	**TYP.**	**MAX.**	**UNIT**
Static						
Drain-Source Breakdown Voltage	V_{DS}	V_{GS} = 0 V, I_D = 250 µA	100	-	-	V
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	I_D = 250 µA	-	165	-	mV/°C
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}/T_J$		-	-11	-	
Gate-Source Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250 µA	2.5	-	4.4	V
Gate-Source Leakage	I_{GSS}	V_{DS} = 0 V, V_{GS} = ± 20 V	-	-	± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 100 V, V_{GS} = 0 V	-	-	1	µA
		V_{DS} = 100 V, V_{GS} = 0 V, T_J = 55 °C	-	-	10	
On-State Drain Current [a]	$I_{D(on)}$	$V_{DS} \geq$ 5 V, V_{GS} = 10 V	40	-	-	A
Drain-Source On-State Resistance [a]	$R_{DS(on)}$	V_{GS} = 10 V, I_D = 12 A	-	0.0210	0.0260	Ω
		V_{GS} = 7 V, I_D = 8 A	-	0.0285	0.0375	
Forward Transconductance [a]	g_{fs}	V_{DS} = 15 V, I_D = 12 A	-	25	-	S
Dynamic [b]						
Input Capacitance	C_{iss}	V_{DS} = 12 V, V_{GS} = 0 V, f = 1 MHz	-	2000	-	pF
Output Capacitance	C_{oss}		-	180	-	
Reverse Transfer Capacitance	C_{rss}		-	60	-	
Total Gate Charge	Q_g	V_{DS} = 50 V, V_{GS} = 10 V, I_D = 12 A	-	31	47	nC
Gate-Source Charge	Q_{gs}		-	10	-	
Gate-Drain Charge	Q_{gd}		-	9	-	
Gate Resistance	R_g	f = 1 MHz	-	1.5	-	Ω
Turn-On Delay Time	$t_{d(on)}$	V_{DD} = 50 V, R_L = 5 Ω $I_D \cong$ 10 A, V_{GEN} = 10 V, R_g = 1 Ω	-	10	15	ns
Rise Time	t_r		-	10	15	
Turn-Off Delay Time	$t_{d(off)}$		-	15	25	
Fall Time	t_f		-	10	15	
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I_S	T_C = 25 °C	-	-	50	A
Pulse Diode Forward Current [a]	I_{SM}		-	-	40	
Body Diode Voltage	V_{SD}	I_S = 10 A	-	0.8	1.2	V
Body Diode Reverse Recovery Time	t_{rr}	I_F = 10 A, di/dt = 100 A/µs, T_J = 25 °C	-	50	75	ns
Body Diode Reverse Recovery Charge	Q_{rr}		-	100	150	nC
Reverse Recovery Fall Time	t_a		-	38	-	ns
Reverse Recovery Rise Time	t_b		-	12	-	

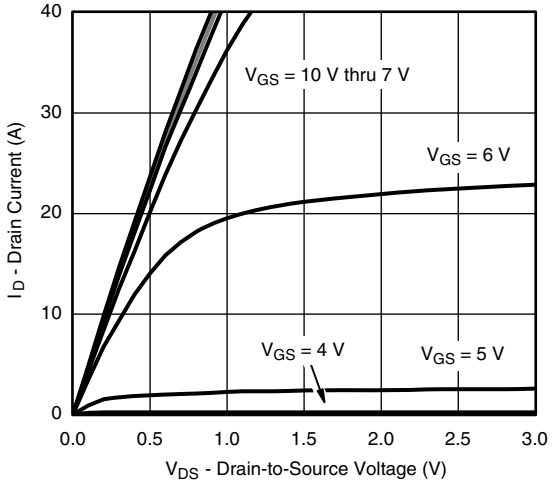
Note

a. Pulse test; pulse width ≤ 300 µs, duty cycle ≤ 2 %.

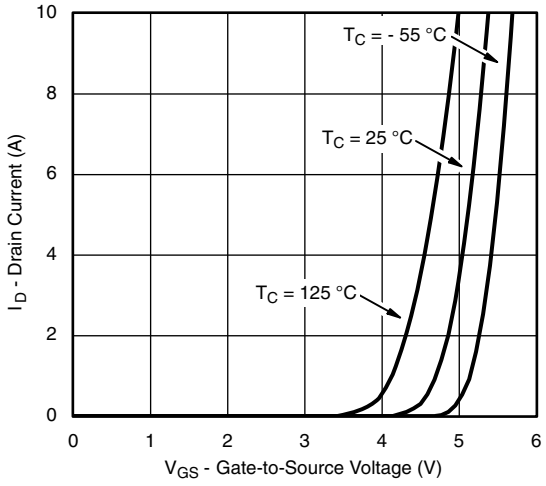
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

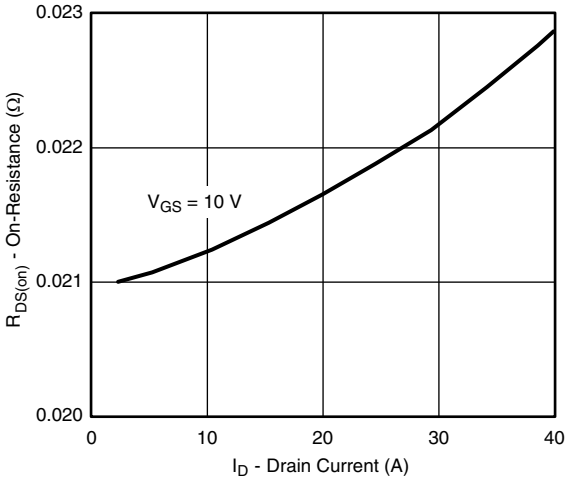
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



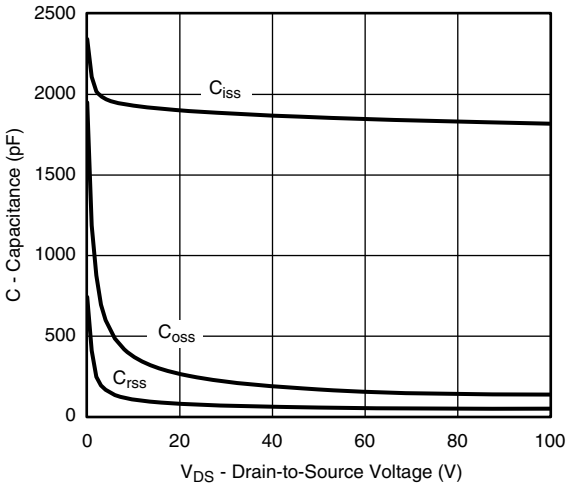
Output Characteristics



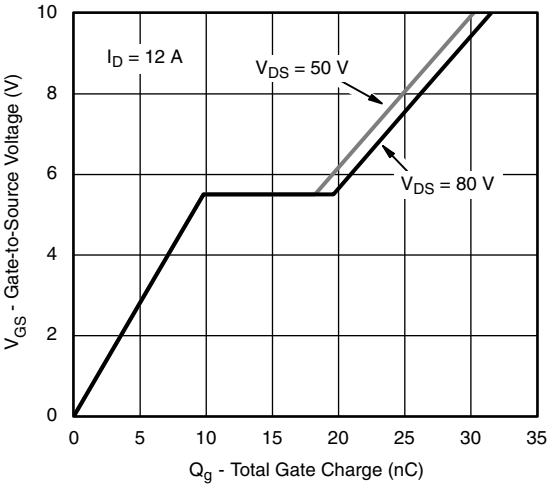
Transfer Characteristics



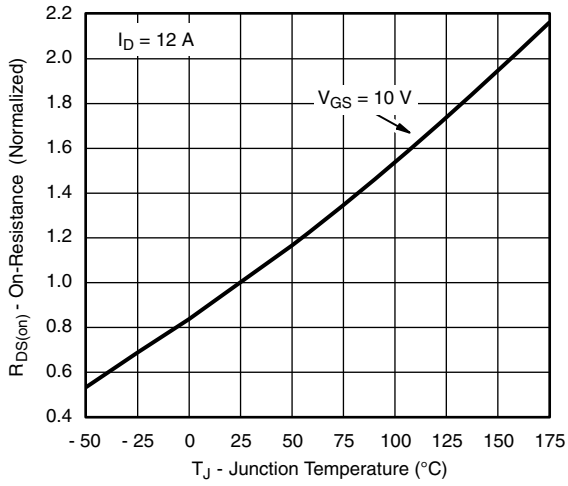
On-Resistance vs. Drain Current



Capacitance

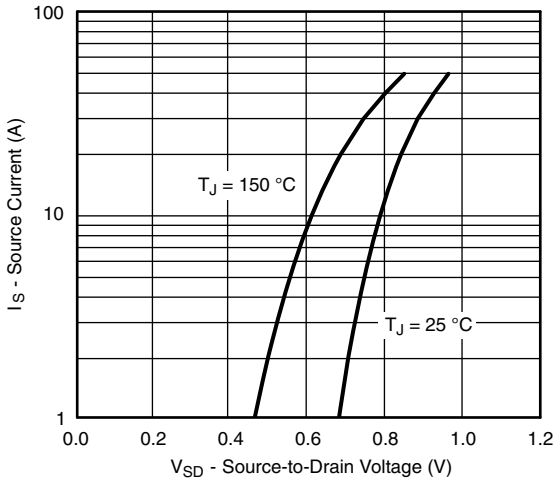


Gate Charge

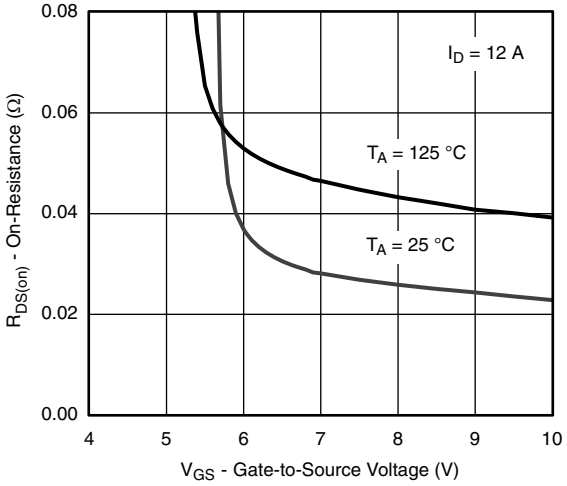


On-Resistance vs. Junction Temperature

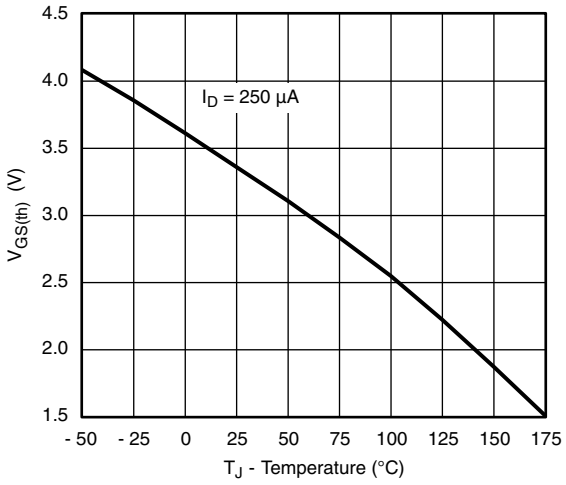
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



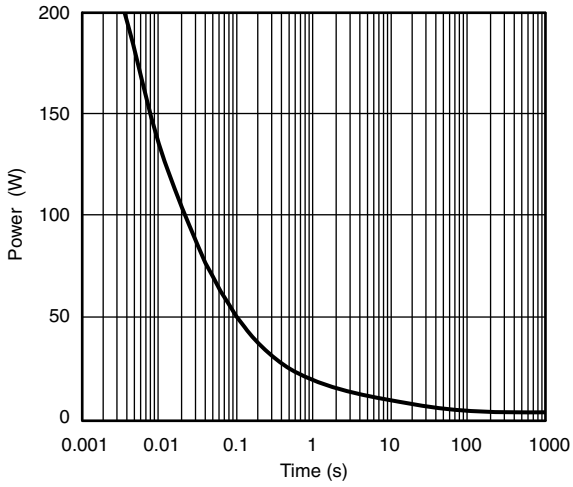
Source-Drain Diode Forward Voltage



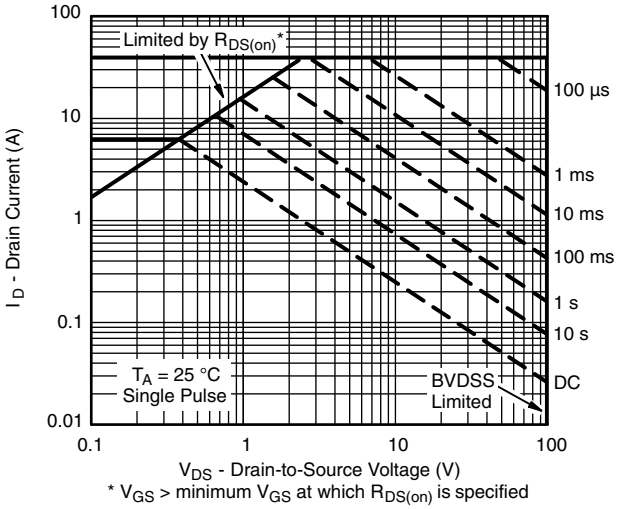
$R_{DS(on)}$ vs. V_{GS} vs. Temperature



Threshold Voltage



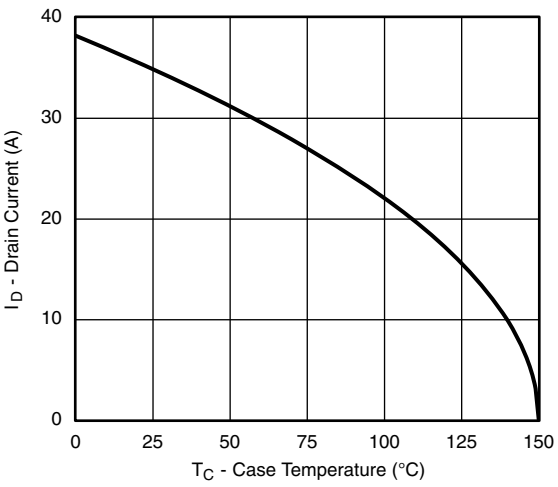
Single Pulse Power, Junction-to-Ambient



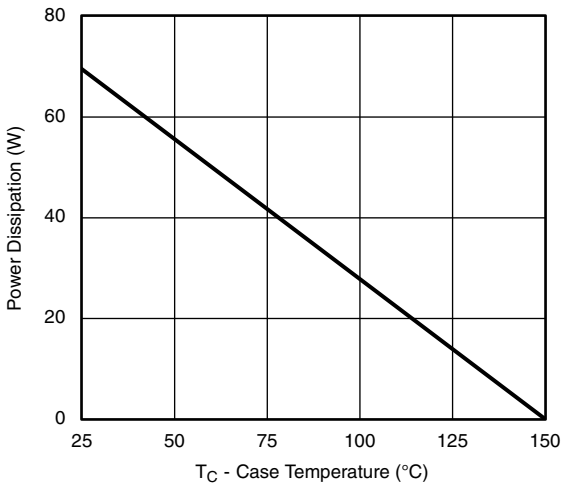
* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Current Derating [a]

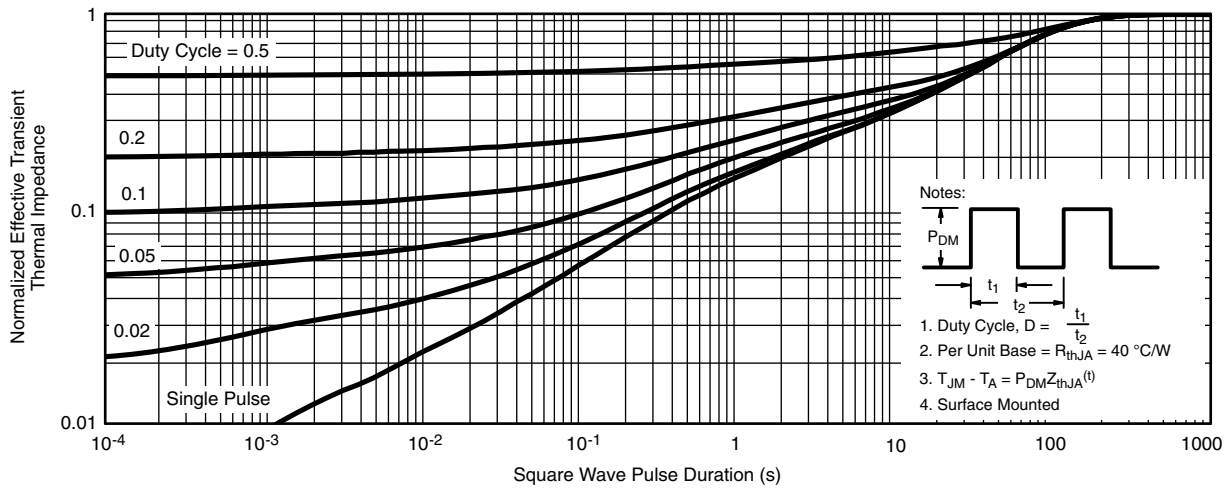


Power Derating

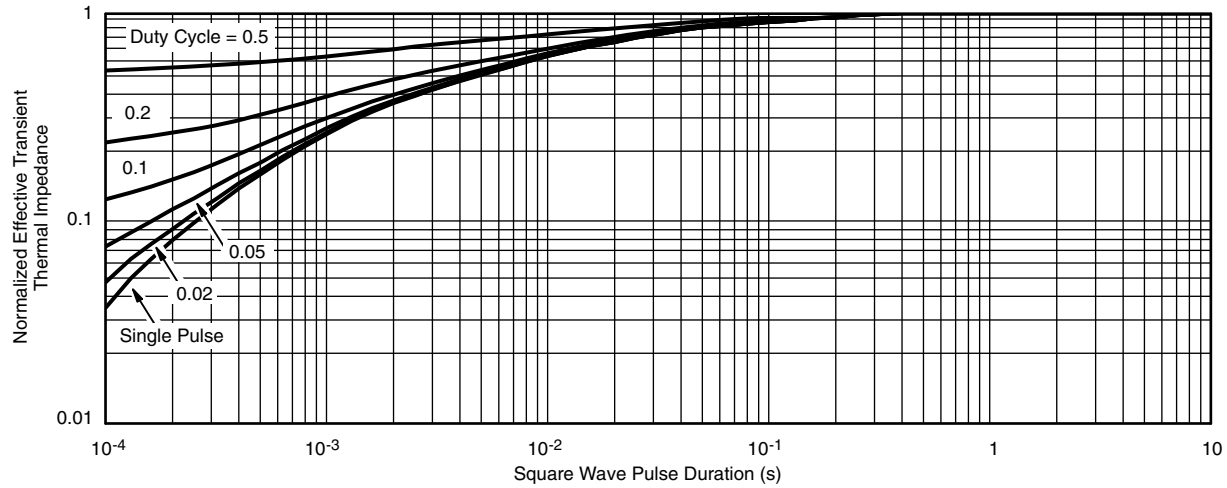
Note

a. The power dissipation P_D is based on T_J (max.) = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient

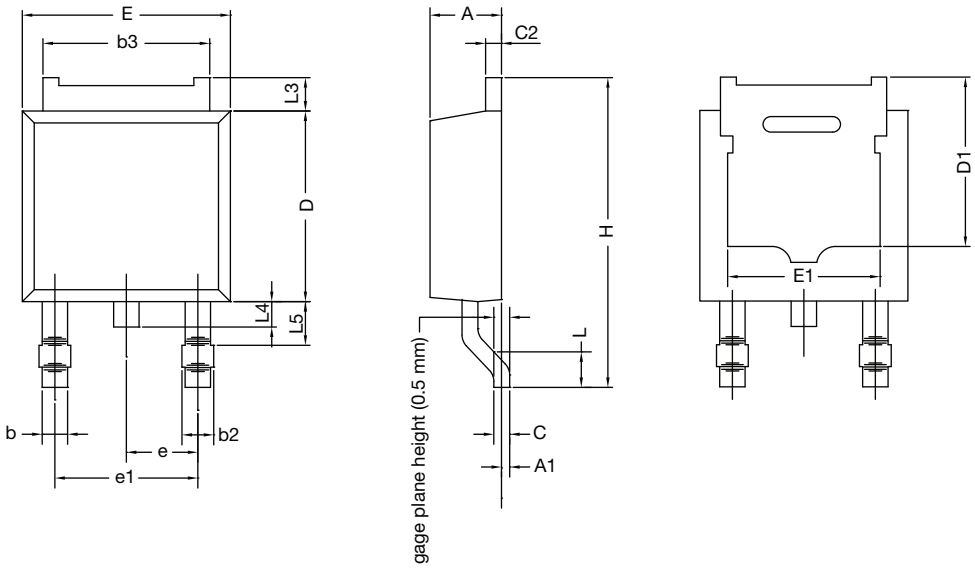


Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?69796.

TO-252AA Case Outline

VERSION 1: FACILITY CODE = Y

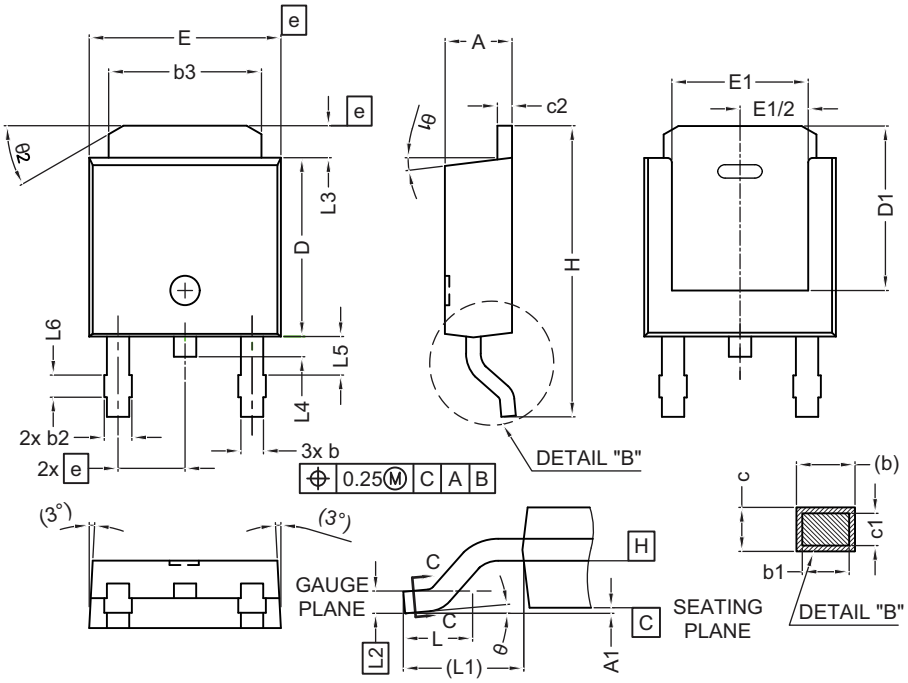


	MILLIMETERS	
DIM.	MIN.	MAX.
A	2.18	2.38
A1	-	0.127
b	0.64	0.88
b2	0.76	1.14
b3	4.95	5.46
C	0.46	0.61
C2	0.46	0.89
D	5.97	6.22
D1	4.10	-
E	6.35	6.73
E1	4.32	-
H	9.40	10.41
e	2.28 BSC	
e1	4.56 BSC	
L	1.40	1.78
L3	0.89	1.27
L4	-	1.02
L5	1.01	1.52

Note

- Dimension L3 is for reference only

VERSION 2: FACILITY CODE = N



	MILLIMETERS	
DIM.	MIN.	MAX.
A	2.18	2.39
A1	-	0.13
b	0.65	0.89
b1	0.64	0.79
b2	0.76	1.13
b3	4.95	5.46
c	0.46	0.61
c1	0.41	0.56
c2	0.46	0.60
D	5.97	6.22
D1	5.21	-
E	6.35	6.73
E1	4.32	-
e	2.29 BSC	
H	9.94	10.34

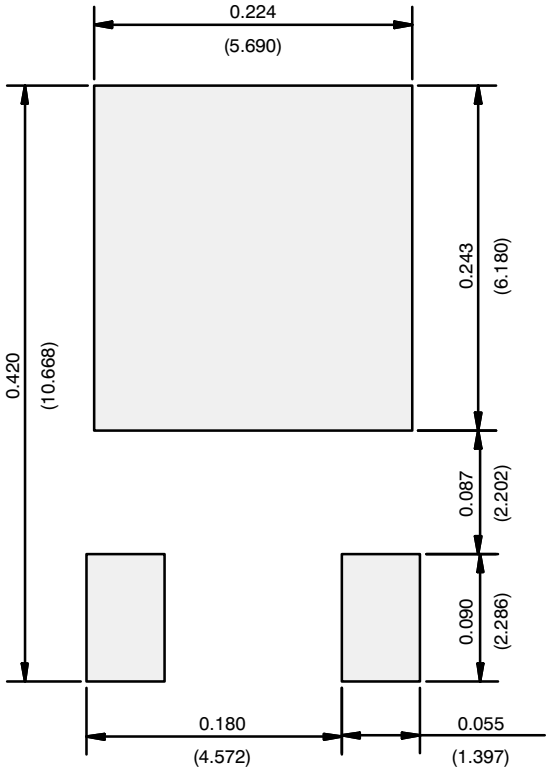
	MILLIMETERS	
DIM.	MIN.	MAX.
L	1.50	1.78
L1	2.74 ref.	
L2	0.51 BSC	
L3	0.89	1.27
L4	-	1.02
L5	1.14	1.49
L6	0.65	0.85
θ	0°	10°
θ1	0°	15°
θ2	25°	35°

Notes

- Dimensioning and tolerance confirm to ASME Y14.5M-1994
- All dimensions are in millimeters. Angles are in degrees
- Heat sink side flash is max. 0.8 mm
- Radius on terminal is optional

ECN: E22-0399-Rev. R, 03-Oct-2022
DWG: 5347

RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads
Dimensions in Inches/(mm)

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